

WHAT IS CLAIMED IS:

*Rule 1.26* 1. An apparatus for mounting a semiconductor device on a wiring board, which apparatus comprising:

5 a compression bonding head relatively movable to a table on which the wiring board is placed; and

a press head provided with holding means whereby a pressing chip for forming a concave of a predetermined size in an insulating adhesive layer, which has been tentatively thermocompression bonded onto said wiring board, and said semiconductor device are held respectively.

10 2. The apparatus as claimed in claim 1, wherein said compression bonding head is constructed as serving both as said press head.

3. The apparatus as claimed in claim 2, wherein said holding means are constructed as holding respectively said pressing chip and said semiconductor device in a removal manner.

15 4. The apparatus as claimed in claim 3, wherein said holding means are constructed as sucking the air via a suction hole formed in the compression bonding part of said compression bonding head.

5. The apparatus as claimed in claim 4, wherein the compression bonding part of said compression bonding head is provided with plural suction holes.

20 6. The apparatus as claimed in claim 5, wherein the face of said pressing chip in contact with said insulating adhesive layer is releasable from said insulating adhesive.

7. The apparatus as claimed in claim 6, wherein the face of said pressing chip in contact with said insulating adhesive layer is releasable from said insulating adhesive.

25 8. The apparatus as claimed in claim 7, wherein the face of said pressing chip in contact with said insulating adhesive layer is releasable from said insulating adhesive.

30 9. The apparatus as claimed in claim 8, wherein the face of said pressing chip in contact with said insulating adhesive layer is releasable from said insulating adhesive.

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